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	5902-0	903 IC	ЛПЛ		+1四日	ESCR	IPTIO	N					DA	ATE (Y	R-MO-E	)A)		APPF	OVED	
A		Added CAGE number 50507. Added device types 03 and 04, and case outline Y, (figure 2). Corrected table I gain error (GE).						91-01-25			W. Heckman		۱							
В	Char	nges ir	acco	rdance	e with	NOR 5	5962-F	R017-9	91.					91-1	0-07			G. A	Lude	
с	Char	nges ir	acco	rdance	e with	NOR 5	5962-F	157-9	92.					92-0	3-12			A. B	arone	
D	Char	nges ir	acco	rdance	e with	NOR 5	5962-F	3111-9	94					94-0	2-04		K	(. A. C	ottong	m
E	Char	nges ir	acco	rdance	e with	NOR 5	5962-F	R127-9	94.					94-0	3-15		K	(. <b>A.</b> C	ottong	m
F	Char	nges ir	n acco	rdance	e with	NOR 5	5962-F	3200-9	94.					94-0	5-31		K	(. A. C	ottong	m
G	Char	nges ir	1 acco	rdance	e with	NOR 5	<u>5962-F</u>	R201-9	95				<u>-</u>	<u>95-0</u>	9-29		k	(. A. C	ottong	<u>m_</u>
н	Corr	ect ca	se out	line X	packa	<u>ge hei</u> g	ght dir	nensio	m		t			97-0	<del>9-</del> 10		<u> </u>	(. A. C	ottong	m
J	Tabl	<u>e I, ch</u>	ange r	naxim	um limi	its to L	E and	I UOE	tests.					98-0	1-22		ŀ	(. A. C	ottong	im
REV SHEET																			1	
SHEET	J																			
SHEET REV SHEET	15																			
SHEET	15 US			RE	V EET		 J	J	J		J 5	J	J	J	J	J 10	J 11	J 12	J 13	
SHEET REV SHEET REV STAT	15 US			SHI				+			5	6	7	8 JPPLY	9 ( CEN	J 10 TER ( 3990	11 OLUI	12	13	
SHEET REV SHEET REV STAT OF SHEET PMIC N/A STA		CUI	<b>T</b>	SHI PREI Dona	EET	sborne 3Y		+			5	6 EFEN	7 SE SL	8 JPPLY P. O	9 ( CEN ). BOX	10 TER 0	11 COLUI	12 MBUS	13	
SHEET REV SHEET REV STAT OF SHEET PMIC N/A STA MICR DR THIS DRA FOF	15 TUS TS ANDA OCIR BAWIN BAWIN SUSE BY	CUI NG VAILAB		SHI PREI Dona CHE Ro	EET PARED ald R. O CKED E bert M. I	sborne 3Y Heber	1	+		4 MIC	5 DI ROCIF	6 EFENS	7 SE SU COLUI	8 JPPLY P. O MBUS	9 ( CEN ). BOX ), OHIO	10 TER ( 3990	11 COLUI	12 MBUS	13	1
SHEET REV SHEET REV STAT OF SHEET PMIC N/A STA MICR DR THIS DRA FOF DE	15 US TS ANDA OCIR ANDA OCIR AUSE BY PARTMEN ENCIES (	CUI NG VAILAB ALL ITS DF THE	LE	SHI Dona CHEI Roi APPI Will	EET PARED ald R. O CKED E bert M. I ROVED llam K. I	sborne 3Y Heber BY Heckma		2		4 MICI ANA	5 DI ROCIF	6 EFENS CONV	7 SE SU COLUI , HYE ERTE	8 JPPLY P. O MBUS SRID, R	9 ( CEN ). BOX ), OHIO	10 TER ( 3990 2 432	11 <b>:OLUI</b> 16-50	12 MBUS DO	13 AL TC	1
SHEET REV SHEET REV STAT OF SHEET PMIC N/A STA MICR DR THIS DRAY FOR DEI AND AG DEPARTM	15 US TS ANDA OCIR ANDA OCIR AUSE BY PARTMEN ENCIES (	CUI NG VAILAB ALL ITS DF THE	LE	SHI PRE Dona CHE Ro APPI Will DRA	EET PARED ald R. O CKED E bert M. I ROVED llam K. I	Sborne 3Y Heber BY Heckma VPPROV 90-0	1 	2		4 MICI ANA	5 DI ROCIF	6 EFENS CONV	7 SE SU COLUI , HYE ERTE	8 JPPLY P. O MBUS BRID, R	9 ( CEN ). BOX ), OHIO	10 TER ( 3990 2 432	11 COLUI	12 MBUS DO	13 AL TC	1

APR 97

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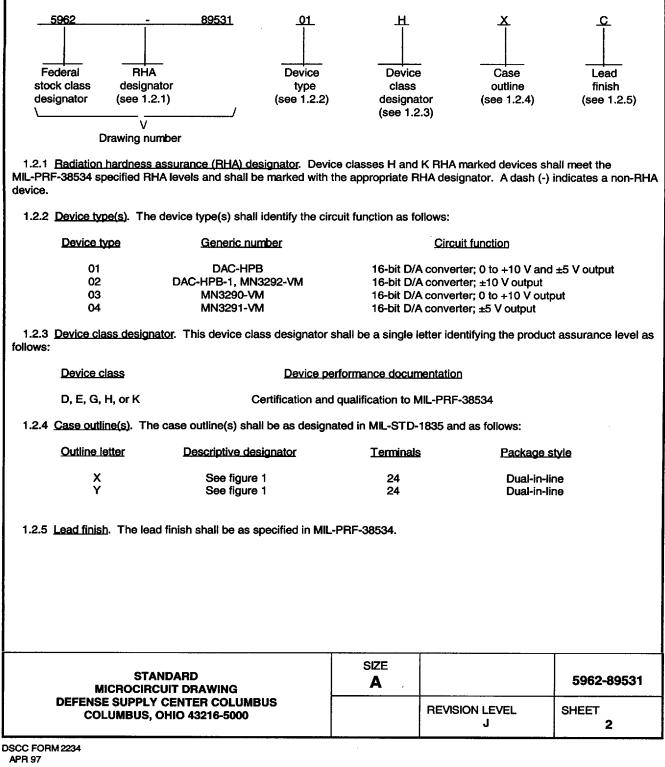
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# 查询9962-8953101HXC"供应商

1.1 <u>Scope</u>. This drawing documents five product assurance classes, class D (lowest reliability), class E, (exceptions), class G (lowest high reliability), class H (high reliability), and class K, (highest reliability) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.

1.2 PIN. The PIN shall be as shown in the following example:



**9**004708 0033906 634 **ES** 

# 查询 4598/2-89537071 日 2008 供应商

<b>Depiking complementation <math>(M_{ij})</math></b>	
Positive supply voltage (V <sub>CC</sub> )	-0.3 to +18 V dc
Negative supply voltage (V <sub>EE</sub> )	+0.3 to -18 V dc
Digital inputs (pins 1 through 16)	+5.5 V
Output current	±20 mA
Analog output voltage	±18 V (supply voltage)
Junction temperature (T <sub>J</sub> )	+175°C
Storage temperature	-65°C to +150°C
Lead temperature (soldering, 10 seconds0	+300°C
Power dissipation (P <sub>D</sub> )	1.35 W
Thermal resistance:	
Junction-to-case (θ <sub>JC</sub> )	13°C/W
Junction-to-ambient (9JA)	49°C/W

1.4 <u>Recommended operating conditions</u>.

Supply voltage ranges:	
Positive supply voltage (V <sub>CC</sub> )	+14.5 V to +15.5 V dc
Negative supply voltage (VEE)	-14.5 V to -15.5 V dc
Ambient operating temperature range (T <sub>A</sub> )	-55°C to +125°C

## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification. standards, and handbook</u>. The following specification, standards, and handbook form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solitation.

#### SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Methods and Procedures for Microelectronics. MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.

#### HANDBOOK

DEPARTMENT OF DEFENSE

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbook are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

STANDARD	
MICROCIRCUIT DRAWING	
DEFENSE SUPPLY CENTER COLUMBUS	Γ
COLUMBUS, OHIO 43216-5000	

SIZE <b>A</b>		5962-89531
	REVISION LEVEL J	SHEET 3

DSCC FORM 2234

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## **9004708 0033907 570**

22: Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

### 3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. Therefore, the tests and inspections herein may not be performed for the applicable device class (see MIL-PRF-38534). Futhermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.

3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Analog output data. The analog output data shall be as specified on figure 3.

3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 <u>Marking of Device(s)</u>. Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked as listed in QML-38534.

3.6 <u>Data</u>. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.

3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.

3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

#### 4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000

SIZE A		5962-89531
	REVISION LEVEL J	SHEET 4

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Test	Symbol	Conditions 1/	Group		Limits		Unit	
		-55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	subgrou	ps type	Min	Max		
Resolution	RES	Complementary binary	1, 2, 3	3 01, 03	16		Bits	
Resolution	RES	Complementary offset binary	1, 2, 3	3 01, 02, 04	16		Bits	
Linearity error	LE	Major sums, carries	4	All		0.0038	%FSR	
			5, 6			0.012		
Differential linearity error	DLE	14-bit monotonic	4	Ali		0.006	%FSR	
		13-bit monotonic	5, 6			0.024		
Gain error	GE	$V_0 = +FS$ , +10 V and	4	All		0.1	%FSR	
		±10 V FSR	5, 6			0.24	1	
Unipolar offset error	UOE	$V_{O} = 0 V$ to +10 V range	4	01, 03		0.15	%FSR	
			5, 6			0.20	]	
Bipolar offset error	BOE	V <sub>O</sub> = ±10 V range	4	02		0.1	%FSR	
			5, 6			0.3	1	
		V <sub>O</sub> = ±5 V range	4	01, 04		0.1		
			5, 6			0.3		
Reference error	VREF	V <sub>REF</sub> ≈ 6.300 V ideally	4	All	6.23	6.37	v	
			5, 6		6.2147	6.3826		
Reference current 2/	IREF	For external use, $3/$ T <sub>A</sub> = +25°C	1	All	2		mA	
Slew rate 2/	SR	10 V step, T <sub>A</sub> = +25°C <u>3</u> /	4	Ali	10		mA	
Settling time 2/	t <sub>s</sub>	10 V step to .003% FSR T <sub>A</sub> = +25°C	9	All		20	μs	
		1 LSB step to .003% FSR T <sub>A</sub> = +25°C				15		
Bipolar output voltage, positive (full scale)	+V <sub>BO</sub>	±5 V range, T <sub>A</sub> = +25°C	7	01, 04	+4.	9999	v	
positive (full scale) y		±10 V range, T <sub>A</sub> = +25°C, Input = 0000 0000 0000 000	0	02	+9.9	9999		
See footnotes at end of ta			SIZE	<del>.</del>				
STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000			A		· · · · · · · · · · · · · · · · · · ·	_	2-89531	
				REVISION LE	VEL	SHEET	5	

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Test	Symbol	Conditions <u>1</u> / -55°C ≤ T <sub>A</sub> ≤ +125°C	Group A	Device	Lir	nits	Unit
		unless otherwise specified	subgroups	type	Min	Max	
Bipolar output voltage,	-VBO	±5 V range, T <sub>A</sub> = +25°C	7	01, 04	-5.0	.0000 V	
negative (full scale) 4/		±10 V range, T <sub>A</sub> = +25°C, Input = 1111 1111 1111 1111		02	-10.	0000	
Unipolar output voltage, positive (full scale) <u>4</u> /	+ <sup>V</sup> UO	±10 V range, T <sub>A</sub> = +25°C, Input = 0000 0000 0000 0000	7	01, 03	+9.	9999	v
Unipolar output voltage, negative (full scale) 4/	-vuo	0 to +10 V FSR, T <sub>A</sub> = +25°C, Input = 1111 1111 1111 1111	7	01, 03	0.0	0000	v
Output current	ю	V <sub>O</sub> = ±10 V	4, 5, 6	Ali		±5	mA
Power supply rejectio	PSRR	Worst case, $V_S = \pm 0.5 V$	4, 5, 6	All		0.006	%FSR/ %VS
Supply currents	licc	V <sub>CC</sub> = +15.5 V	1, 2, 3	All		+33	mA
	IEE	V <sub>EE</sub> = -15.5 V				-38	
Power dissipation	PD	V <sub>S</sub> = ±15.5 V	1, 2, 3	All		1100	mW
Digital input voltage high	VIH	lH = +40 μA	1, 2, 3	Ali	2.7		v
Digital input voltage low	VIL	liL = -0.5 mA	1, 2, 3	Ali		0.8	v
Digital input current high	ин	VIH = +2.7 V	1, 2, 3	Ali		+40	μA
Digital input current low	۹L	V <sub>IL</sub> = +0.8 V	1, 2, 3	All		-1.6	mA

2/ Parameter shall be tested as part of device initial characterization and after design and process changes. Parameter shall be guaranteed to the limits specified in table I for all lot(s) not specifically tested.

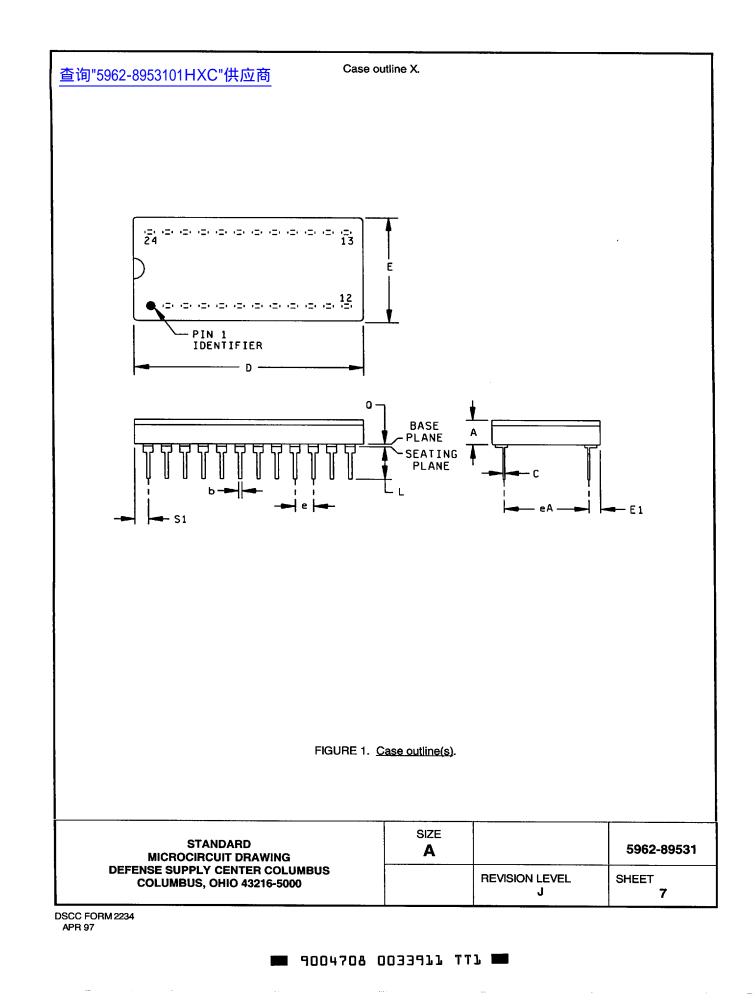
3/ If more than 10 µA is drawn externally, the reference temperature coefficient will increase resulting in a proportional change in the gain and bipolar offset performance.

4/ See figure 4 listing of additional digital input codes to nominal analog outputs.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89531
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		J	6

DSCC FORM 2234 APR 97

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# 查询"5962-8953101HXC"供应商

Case outline X - Continued.

Symbol	Millin	neters	Inc	hes
	Min.	Max.	Min.	Max.
А		4.83		0.190
b		0.46		0.018
С		0.25		0.010
D		33.27		1.310
E	<b></b> '	20.32		0.800
E1/S1		2.54		0.100
е		2.54		0.100
eA		15.24		0.600
L	3.81		0.150	
Q	0.61	0.66	0.024	0.026

### NOTES:

- 1. The U.S. preferred system of measurement is the metric SI. This item was designed using inch-pound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
- 2. Pin numbers are for reference only.

## FIGURE 1. Case outline(s) - Continued.

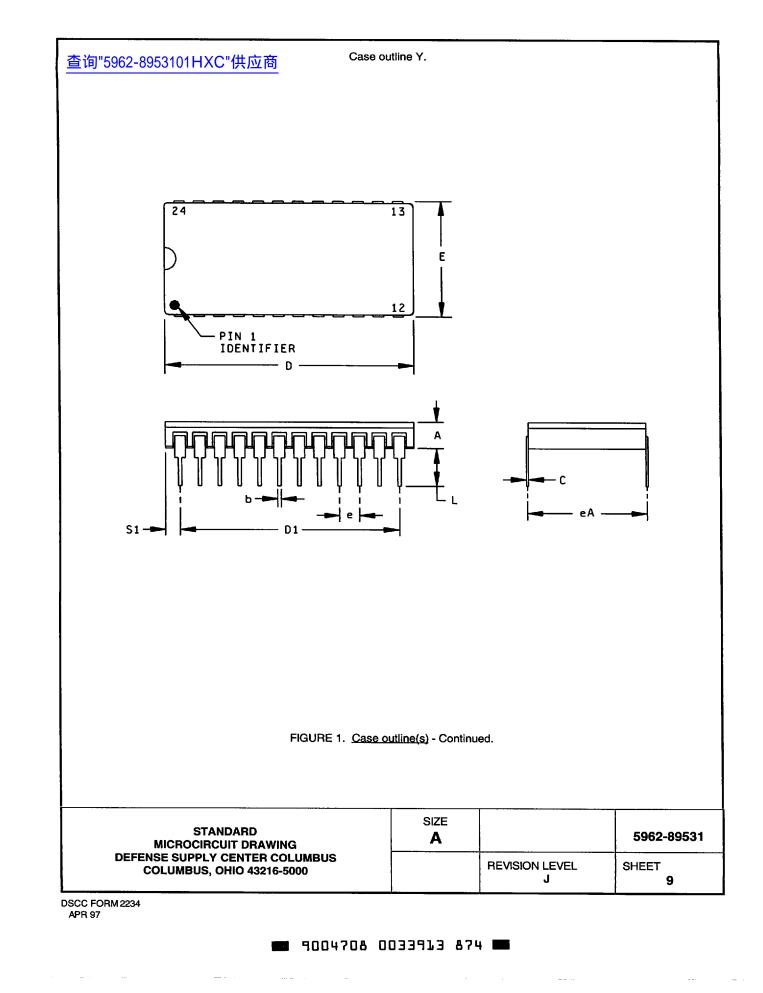
STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89531
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
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# 查询"5962-8953101HXC"供应商

Case outline Y - Continued.

Symbol	Millin	neters	Inc	hes
	Min.	Max.	Min.	Max.
A	3.89	4.65	0.153	0.183
Ь	0.38	0.48	0.015	0.019
С	0.20	0.30	0.008	0.012
D	31.24	32.26	1.230	1.270
D1	27.81	28.07	1.095	1.105
E	15.62	15.87	0.615	0.625
е	2.49	2.59	0.098	0.102
eA	15.11	15.37	0.595	0.605
L	5.08	5.84	0.200	0.230
S1	1.65	2.03	0.065	0.080

## NOTES:

- 1. The U.S. preferred system of measurement is the metric SI. This item was designed using inch-pound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
- 2. Pin numbers are for reference only.

## FIGURE 1. Case outline(s) - Continued.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89531
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
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# 查询"5962-8953101HXC"供应商

Device types	All			
Case outlines	(X, device types 01, 02) and (Y, device types 02, 03, 04)			
Terminal number	Terminal symbol	Terminal number	Terminal symbol	
1	Bit 1 (MSB)	13	Bit 13	
2	Bit 2	14	Bit 14	
3	Bit 3	15	Bit 15	
4	Bit 4	16	Bit 16 (LSB)	
5	Bit 5	17	Output	
6	Bit 6	18	Bipolar offset	
7	Bit 7	19	VEE	
8	Bit 8	20	Ground	
9	Bit 9	21	Sum junction	
10	Bit 10	22	Gain adjust	
11	Bit 11	23	Vcc	
12	Bit 12	24	Reference output	

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FIGURE 2. Terminal connections.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89531
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		J	11

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查询"5962-8953101HXC"供应商 Bipolar operation - complementary offset binary.

Digital in	put code	Scale	Analog output voltage range	
MSB	LSB		Device types 01 and 04, ±5 V range	Device type 02, ±10 V range
0000 0000	0000 0000	+FS -1 LSB	+4.99985 V	+9.99969 V
0011 1111	1111 1111	+1/2 FS	+2.50000 V	+5.00000 V
0111 1111	1111 1111	0	0.00000 V	0.00000 V
1011 1111	1111 1111	-1/2 FS	-2.50000 V	-5.00000 V
1111 1111	1111 1110	-FS +1 LSB	-4.99985 V	-9.99969 V
1111 1111	1111 1111	-FS	-5.00000 V	-10.00000 V

Unipolar operation - complementary binary.

Digital inpu	ut code	Scale	Analog output voltage range
MSB	LSB		Device types 01 and 03, 0 to +10 V range
0000 0000 0 0011 1111 1 0111 1111 1 1011 1111 1 1111 1111 1 1111 1111 1	111 1111 111 1111 111 1111 111 1111 111 1110	+FS -1 LSB +3/4 FS +1/2 FS +1/4 FS +1 LSB 0	+9.99969 V +7.50000 V +5.00000 V +2.50000 V +153 μV 0 V

FIGURE 3. Analog output data.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89531
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		J	12

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	MIL-PRF-38534 test requirer	(in a MIL-P	Subgroups accordance with RF-38534, group A test table)	
Interim electrical parameters			1	
	Final electrical parameters	1*,	, 2, 3, 4, 5, 6, 7	
	Group A test requirements	1, 2,	3, 4, 5, 6, 7, 9**	
	Group C end-point electrical parameters		1	
	MIL-STD-883, group E end-pu electrical parameters for RH devices	A (in a	Subgroups*** cccordance with d 5005, group A test table)	
	<ul> <li>* PDA applies to subgroup 1</li> <li>** Parameter shall be tested and after design and proc to the limits specified in ta</li> </ul>	as part of device ess changes. Pa	arameter shall be guara	nteed
4.2 <u>Screening</u>	*** When applicable to this st the subgroups shall be de Screening shall be in accordance with MIL-PF	andard microcirc fined.	uit drawing,	ria shall apply:
a. Burn-in t (1) Test contri shall	*** When applicable to this st the subgroups shall be de	andard microcirc fined. RF-38534. The f e maintained by t VA or the acquiri	uit drawing, ollowing additional crite he manufacturer under ng activity upon reques	document revision le t. Also, the test circi
a. Burn-in t (1) Test contr shall in tes	*** When applicable to this st the subgroups shall be de Screening shall be in accordance with MIL-PF est, method 1015 of MIL-STD-883. condition A, B, C, or D. The test circuit shall be ol and shall be made available to either DSCC- specify the inputs, outputs, biases, and power	andard microcirc fined. RF-38534. The f e maintained by t VA or the acquiri dissipation, as aj	uit drawing, ollowing additional crite he manufacturer under ng activity upon reques oplicable, in accordance	document revision le t. Also, the test circi
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<ul> <li>a. Burn-in t</li> <li>(1) Test contreshall in tes</li> <li>(2) T<sub>A</sub> as</li> <li>b. Interim a prior to b</li> <li>4.3 <u>Conforman</u></li> </ul>	<ul> <li>*** When applicable to this st the subgroups shall be de</li> <li>Screening shall be in accordance with MIL-PF</li> <li>est, method 1015 of MIL-STD-883.</li> <li>condition A, B, C, or D. The test circuit shall be ol and shall be made available to either DSCC- specify the inputs, outputs, biases, and power it method 1015 of MIL-STD-883.</li> <li>specified in accordance with table I of method nd final electrical test parameters shall be as s</li> </ul>	andard microcirc fined. RF-38534. The f e maintained by t VA or the acquiri dissipation, as ap 1015 of MIL-STE pecified in table I ufacturer.	uit drawing, ollowing additional criter he manufacturer under ng activity upon reques oplicable, in accordance D-883. Il herein, except interim	document revision le t. Also, the test circu e with the intent spec electrical parameter
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查3 "Group Binspection (史)" 例如 解inspection shall be in accordance with MIL-PRF-38534.

4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - (2)  $T_A$  as specified in accordance with table I of method 1005 of MIL-STD-883.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.

4.3.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.

- a. RHA tests for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
- b. End-point electrical parameters shall be as specified in table II herein.
- c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
- d. The devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at T<sub>A</sub> = +25°C ±5 percent, after exposure.
- e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
- f. For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
- g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.
- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.
- 6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89531
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		J	14

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26.2 Replaceability Migrocircuity onversed by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-7603.

6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, P. O. Box 3990, Columbus, Ohio 43216-5000, or telephone (614) 692-0512.

6.6 <u>Sources of supply</u>. Sources of supply are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-89531
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		J	15

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## STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

## DATE: 98-01-22

Approved sources of supply for SMD 5962-89531 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of QML-38534.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-8953101HXC	50721	DAC-HPB/883
5962-8953102HXC	50721	DAC-HPB-1/883
5962-8953102HYA	50507	MN3292-VMYA
5962-8953102HYC	50507	MN3292-VMYC
5962-8953103HYA	50507	MN3290-VMYA
5962-8953103HYC	50507	MN3290-VMYC
5962-8953104HYA	50507	MN3291-VMYA
5962-8953104HYC	50507	MN3291-VMYC

- 1/ The lead finish shown for each PIN, representing a hermetic package, is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine availability.
- 2/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE \_\_\_\_number\_ 50507 Vendor name and address

Micro Networks Company 324 Clarke Street Worcester, MA 01606-1293

50721

Datel, Incorporated 11 Cabot boulevard Mansfield, MA 02048-1194

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.

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